

Fig. 1 Prior Art

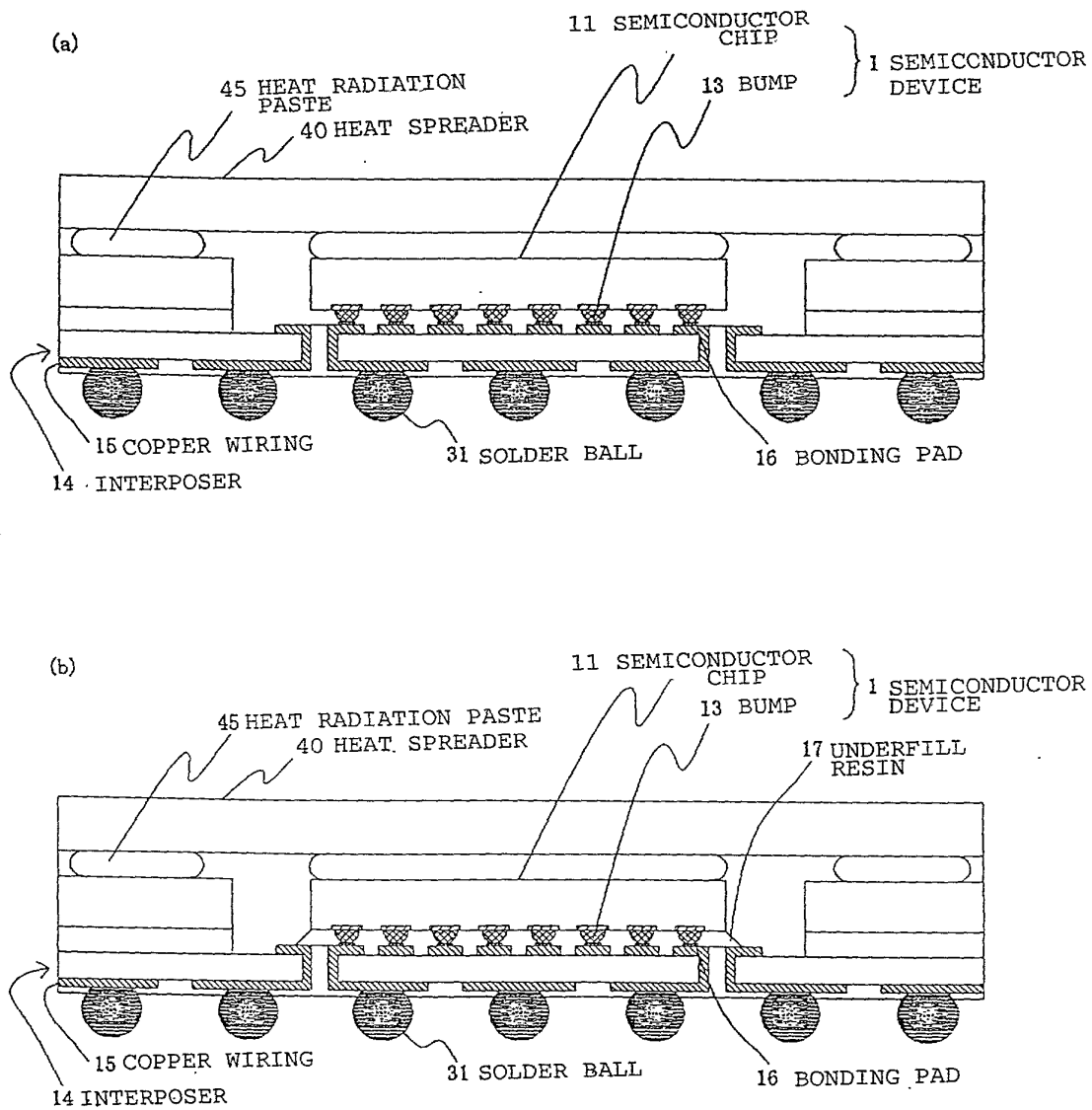
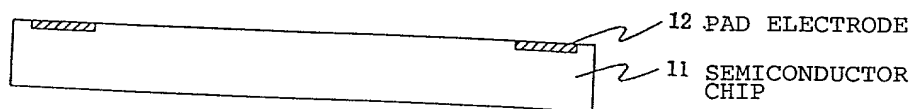
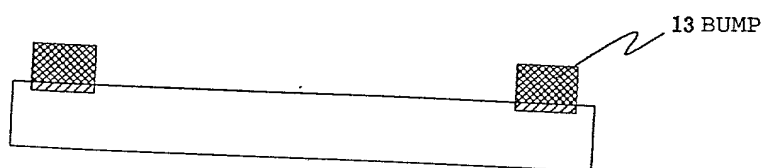


Fig. 2 Prior Art

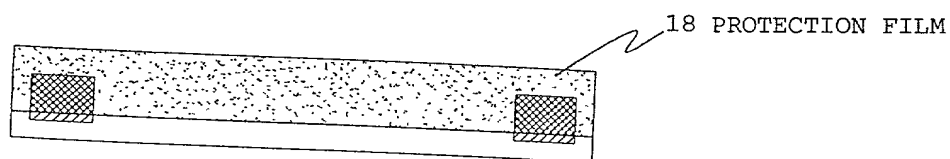
(a)



(b)



(c)



(d)

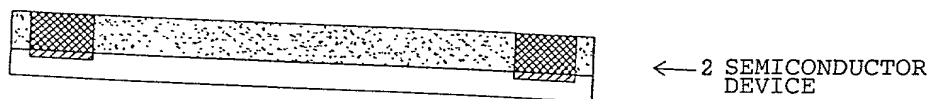
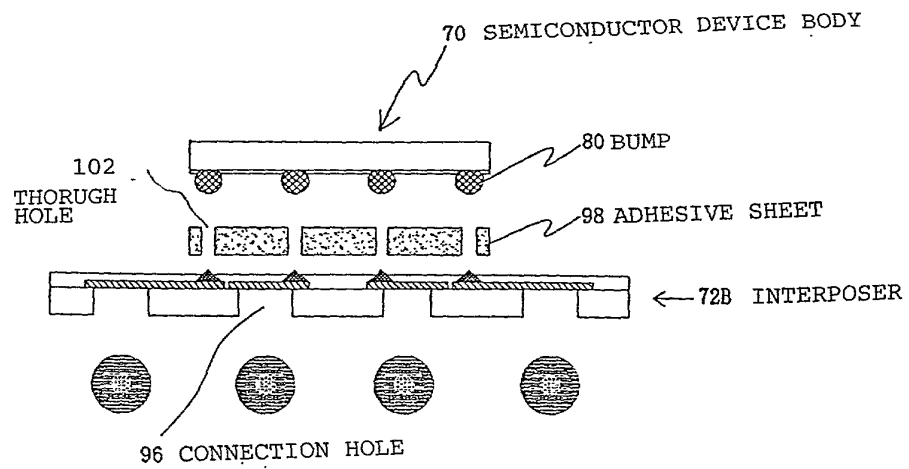


FIG. 2 PRIOR ART

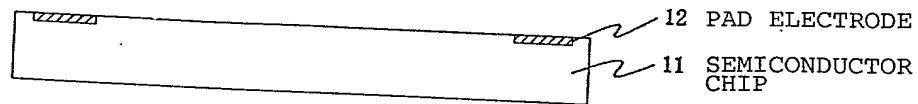
Fig. 3 Prior Art



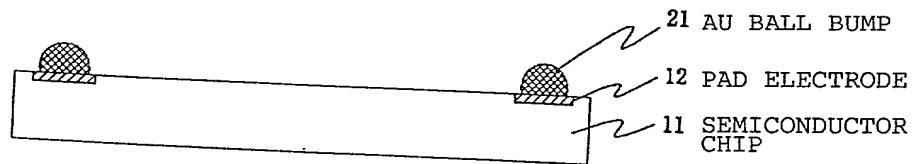
TECHNOLOGY

Fig. 4

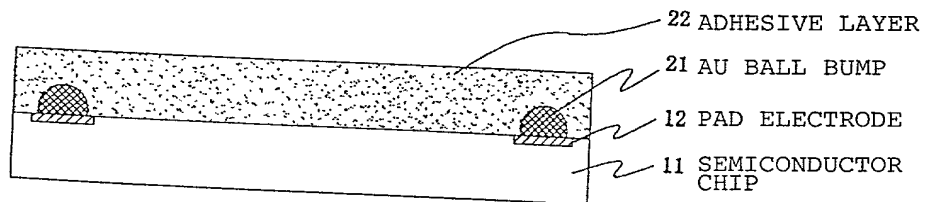
(a)



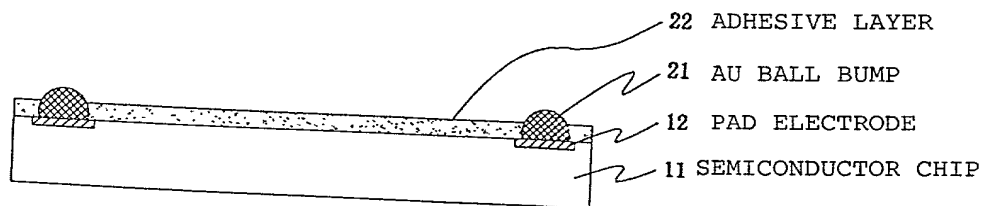
(b)



(c)



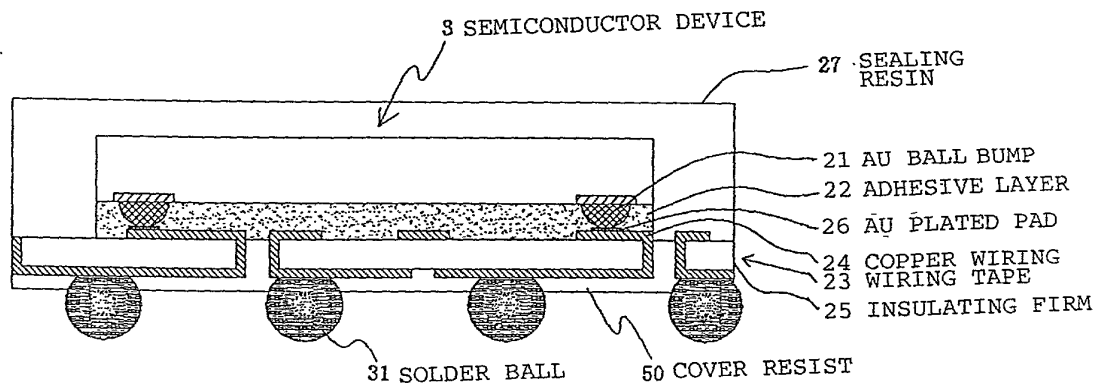
(d)



3 SEMICONDUCTOR DEVICE

Fig. 5

(a)



(b)

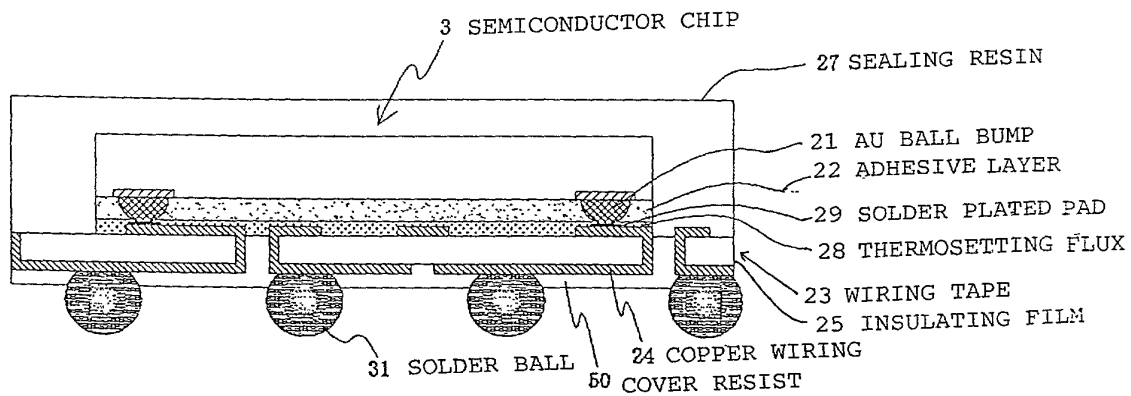


FIG. 5

Fig. 6

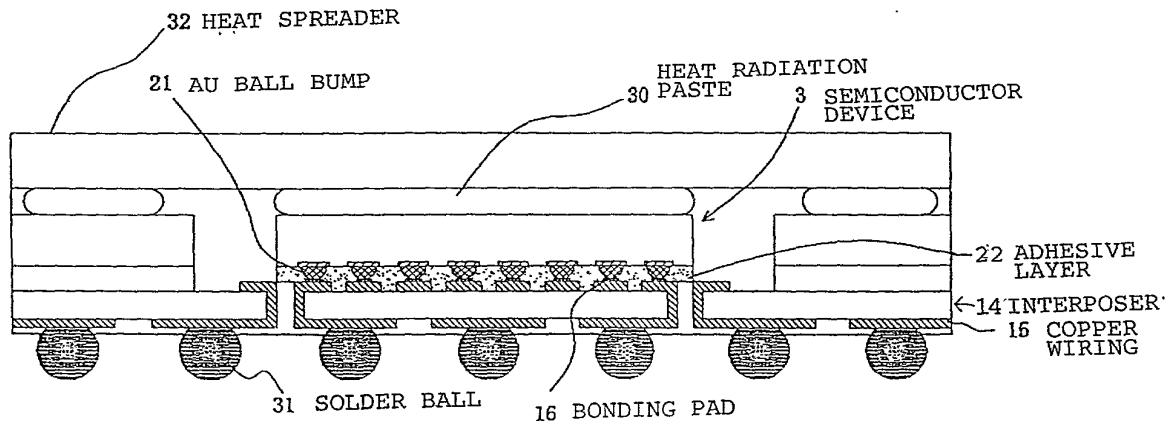


Fig. 7

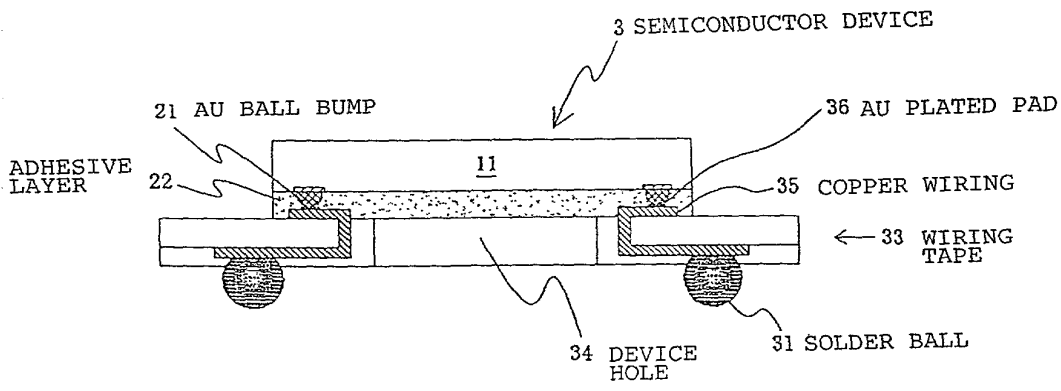


Fig. 8

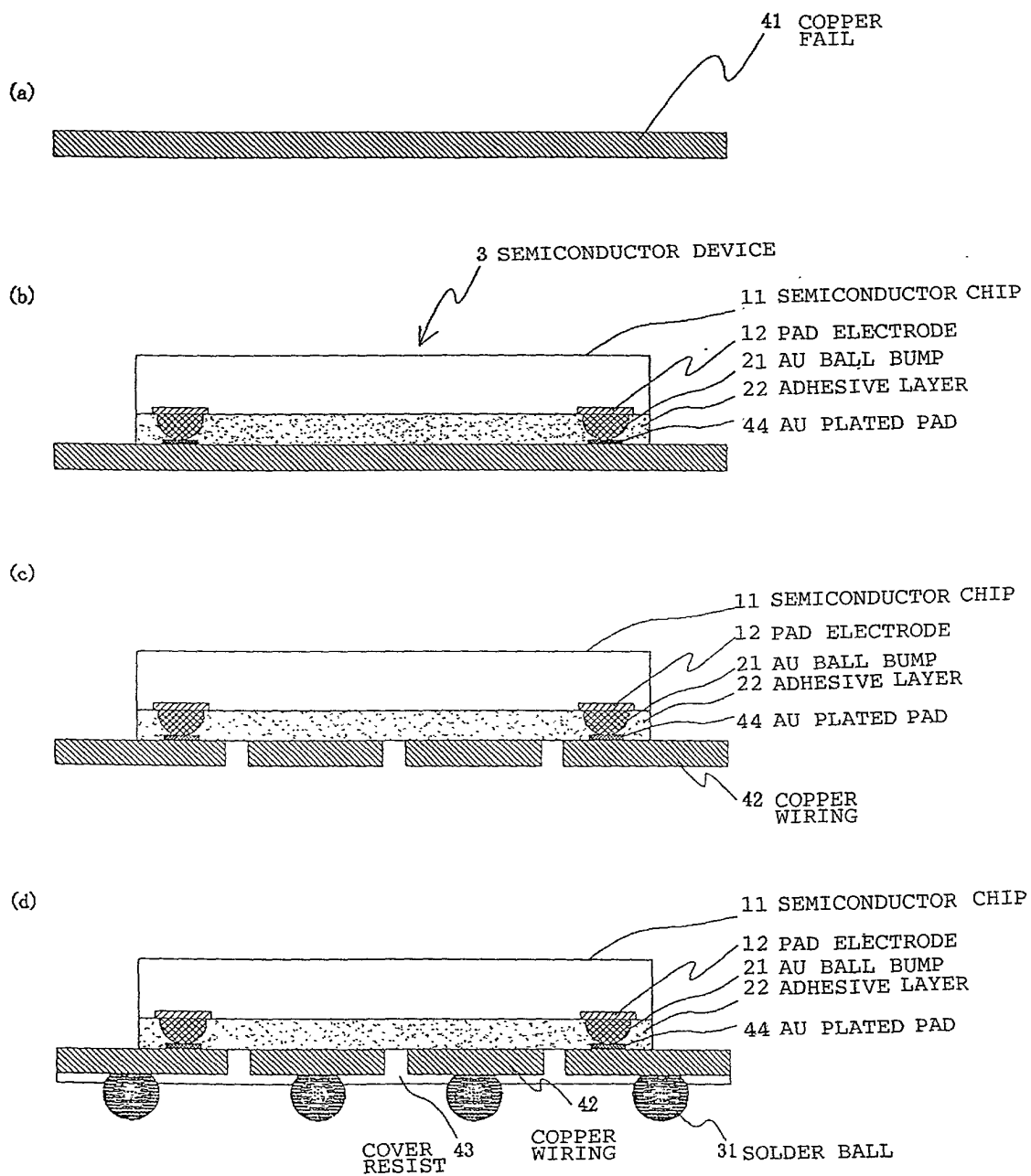
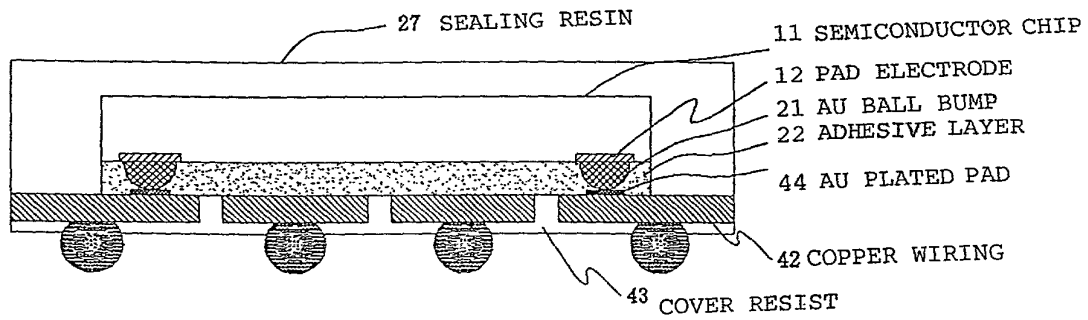


Fig. 9

(a)



(b)

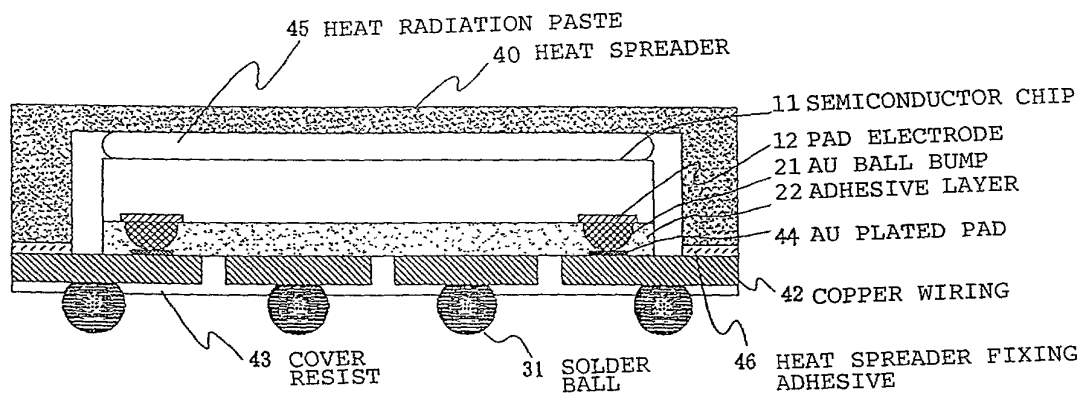


Fig. 10

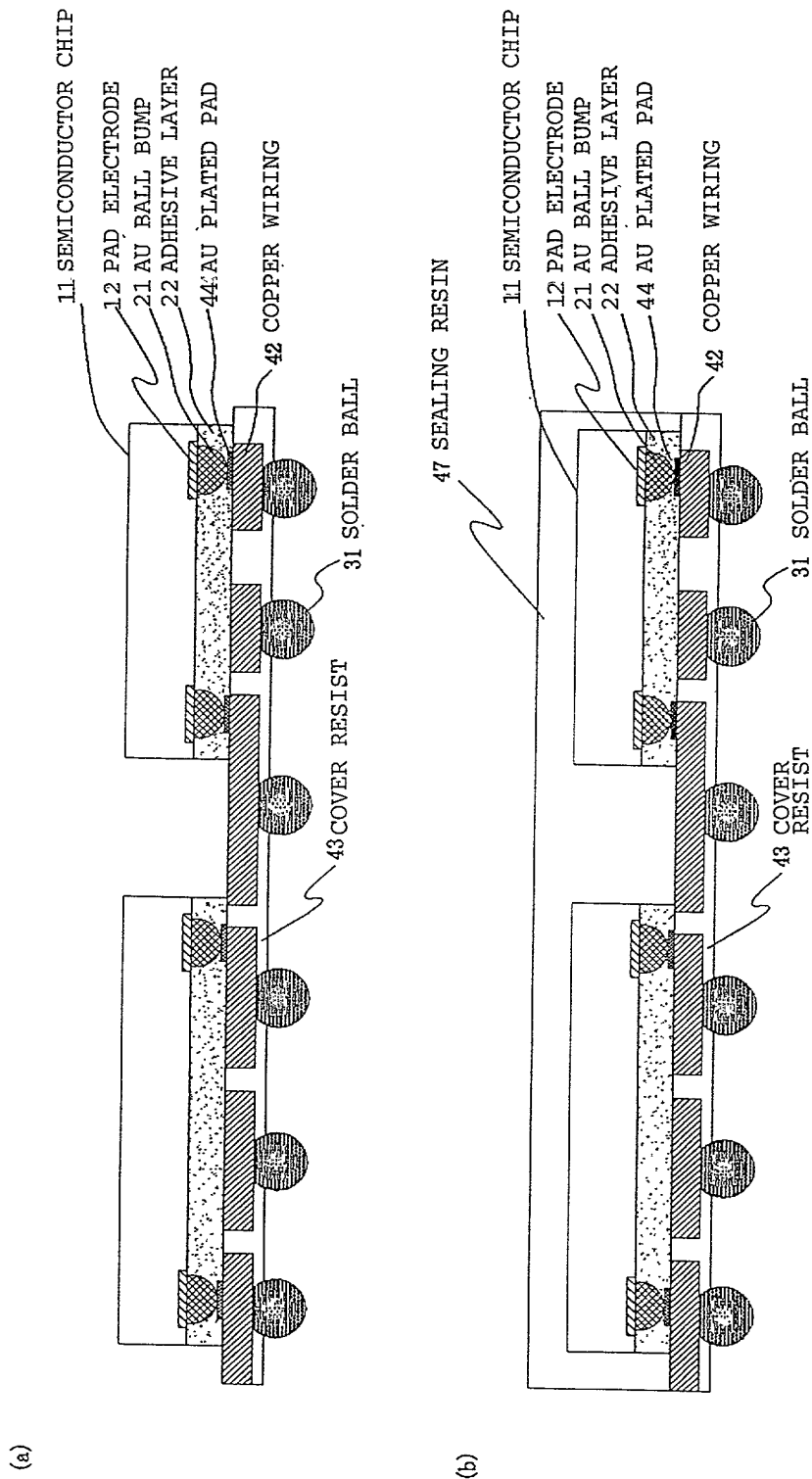


Fig. 11

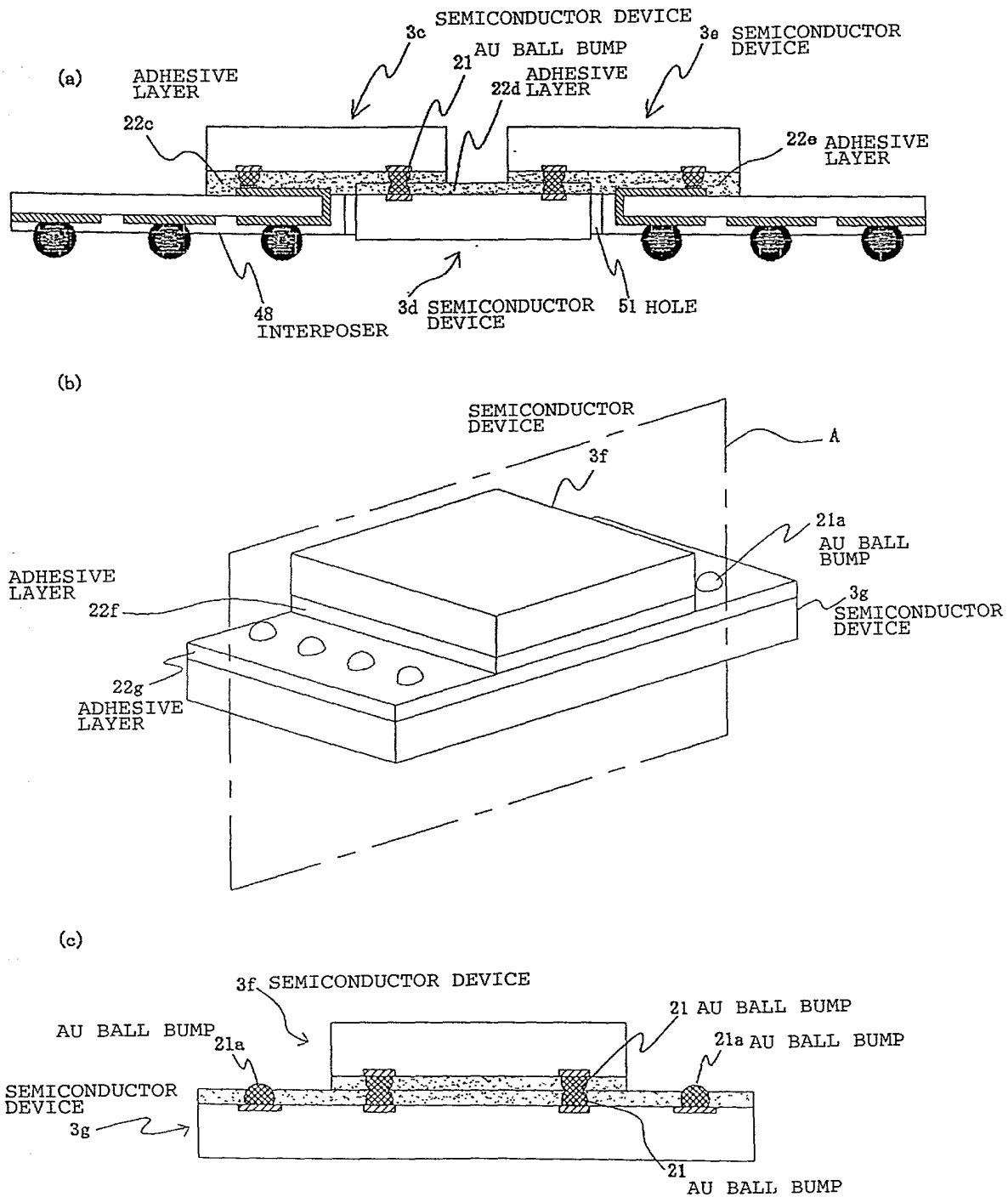


Fig. 12

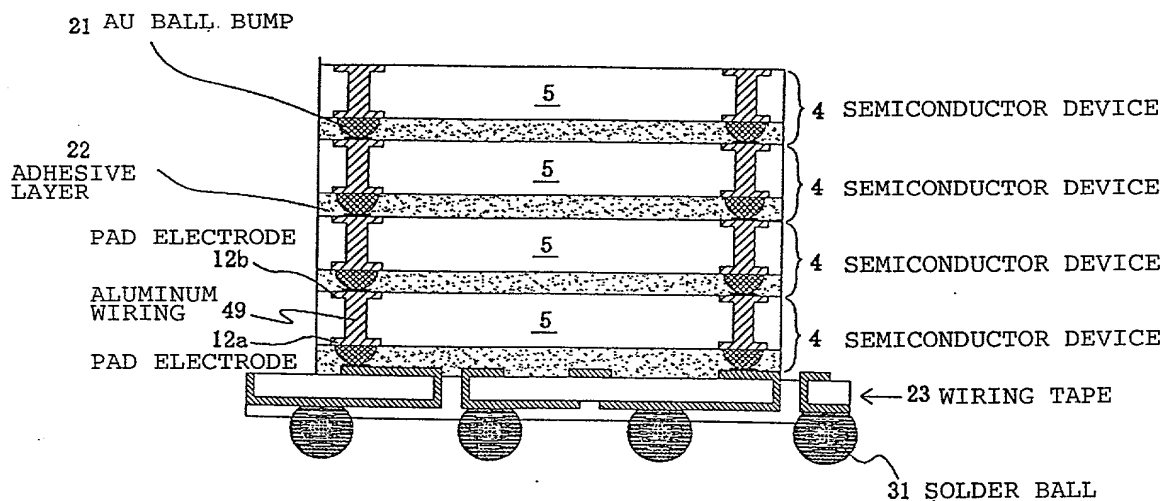


Fig. 13

